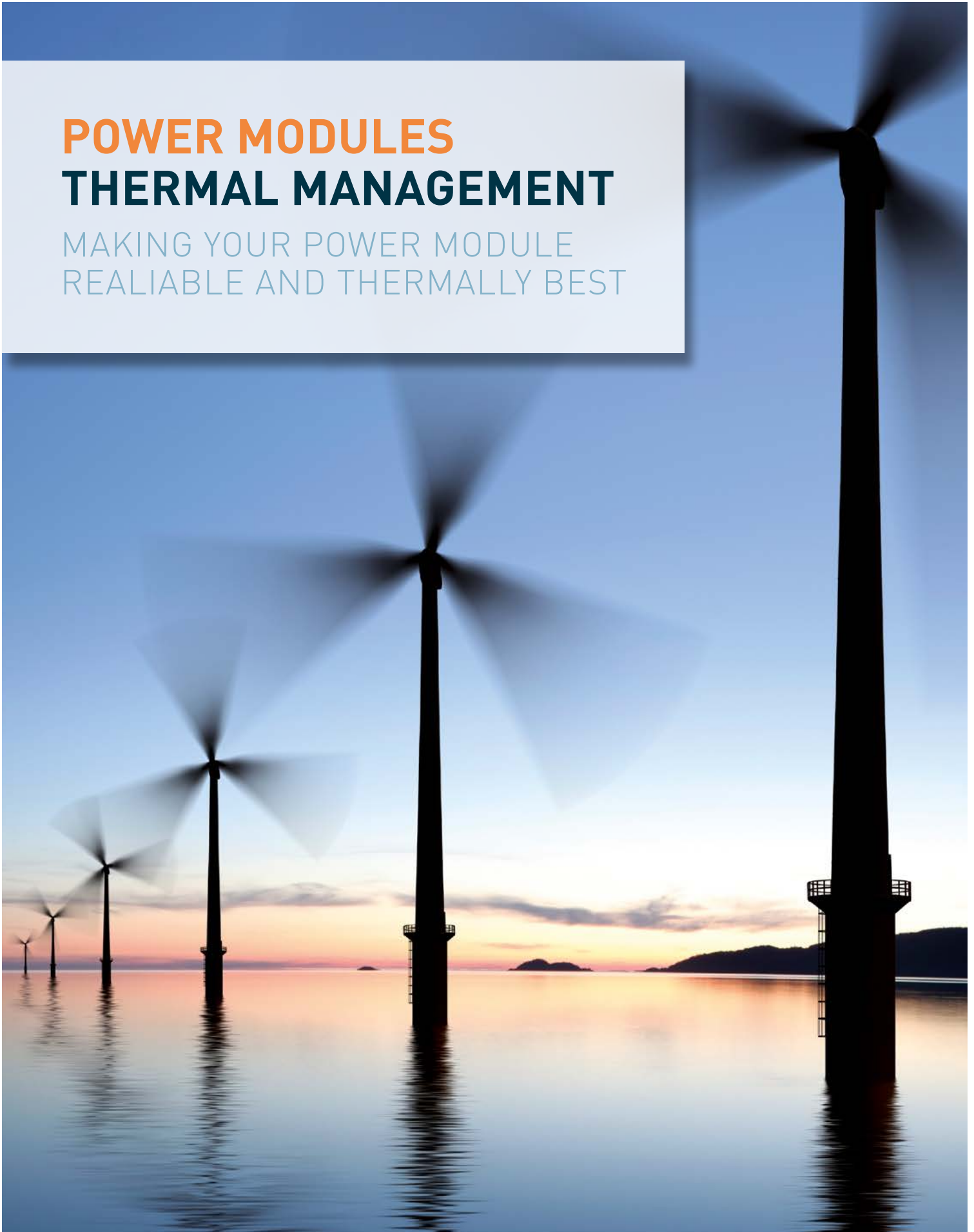


# **POWER MODULES** **THERMAL MANAGEMENT**

MAKING YOUR POWER MODULE  
REALIABLE AND THERMALLY BEST



# POWER MODULES THERMAL MANAGEMENT



MAKING YOUR POWER MODULE RELIABLE AND THERMALLY BEST

## MODULAR CONCEPTS

HALA High Performing Contacting Interface Materials

### Phase Change films

- TPC-Y-PC
- TPC-W-PC
- TPC-T-AL-CB
- TPC-R-AL

### Graphite foil

- TFO-S-CB

### Silicone foil

- TEL-Z-SI

### Silicone grease

- TGR-S-SI

### Graphite foil / pyrolytic

- TFO-Y-PG
- TFO-ZS-PG

### Graphite foil / pyrolytic

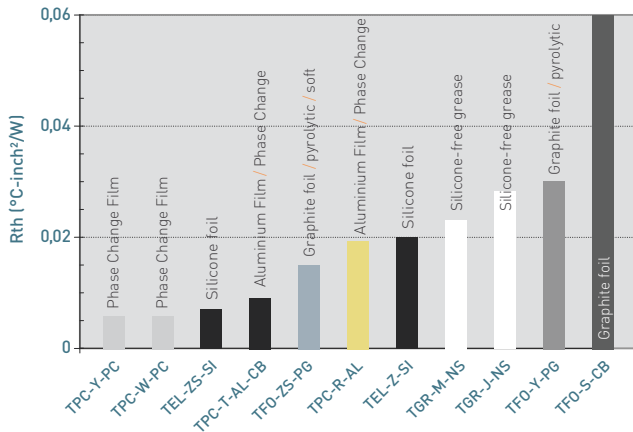
### Silicone-free grease

- TEL-ZS-SI
- TGR-J-NS
- TGR-M-NS

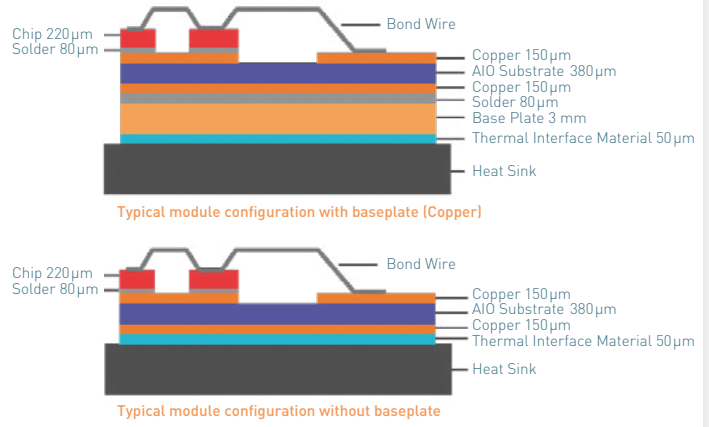


Release 11 / 2024

## ΔT DATA



## CONSTRUCTION DIAGRAM



## CREATING

- Maximum thermal contact
- Minimized thermal resistance
- Compensating mechanic tolerances
- Enhancing efficiency

## BENEFITS

- Increasing long-term reliability
- Minimizing chip temperatures
- Homogenizing chip temperatures
- Pre-applied dry-to-the-touch



Vincotech Module

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